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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		10531611	
	Filing Date		2005-11-04	
	First Named Inventor	Boon Chew Ng		
	Art Unit	1793		
	Examiner Name	Megha S. Mehta		
	Attorney Docket Number	117843.00002		

U.S. PATENTS

Examiner Initial*	Cite No	Patent Number	Kind Code ¹	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
/M.M./	1	6390351		2002-05-21	Kasai, et al.	

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	1					

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FOREIGN PATENT DOCUMENTS

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/M.M./	1	2001-156434	JP		2001-06-08	Hitachi Via Mechanics Ltd.		<input type="checkbox"/>

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NON-PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, pages(s), volume-issue number(s), publisher, city and/or country where published.	T ⁵
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/M.M./	1	"BGA Baller", New Products Section, Circuits Assembly magazine, page 76, July, 1999.	<input type="checkbox"/>
↓	2	"BGA Reballing", SMT magazine, page 67, February, 2000.	<input type="checkbox"/>
	3	"Patent to Vanguard for BGA Sphere-Attach Process", Briefs section, SMT magazine, September, 1996.	<input type="checkbox"/>
	4	Advanced Packaging article. "Void-free, flux-free process for placement and attach of solder balls." February, 2000.	<input type="checkbox"/>

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Examiner Signature	/Megha Mehta/	Date Considered	10/10/2008
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